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(54) Title: DIELECTRIC FILM-FORMING COMPOSITION

(57) Abstract: This disclosure relates to a dielectric film-forming composition that includes (a) at least one resin selected from the group consisting of: i) a fully imidized polyimide polymer; ii) a polyamic acid ester; iii) a cyclized polydiene resin; and iv) a mixture of a cyclized polydiene resin and a cyanate ester compound; and (b) at least one additive selected from a group consisting of: i) a polybenzoxazole (PBO) precursor; ii) PBO particles; iii) a mixture of PBO and silica particles; and iv) a PBO resin containing at least two reactive functional groups.



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